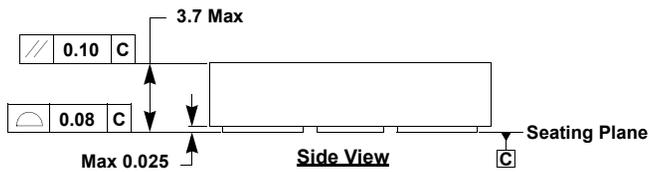
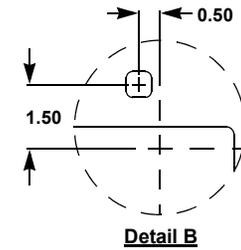
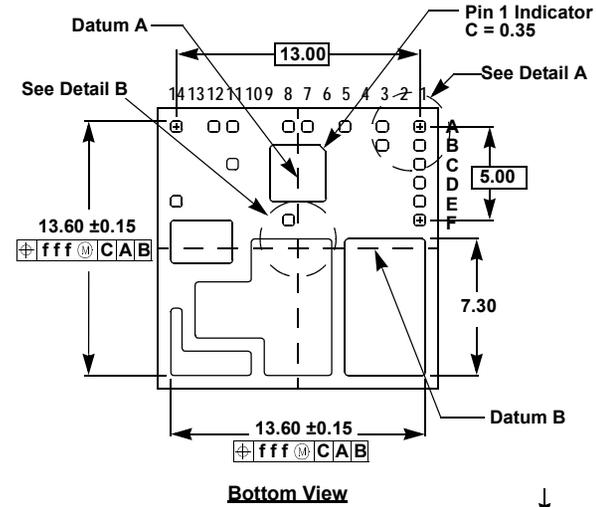
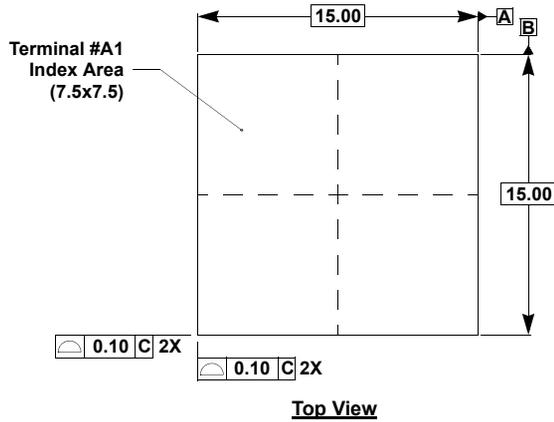


Package Outline Drawing

Y22.15x15

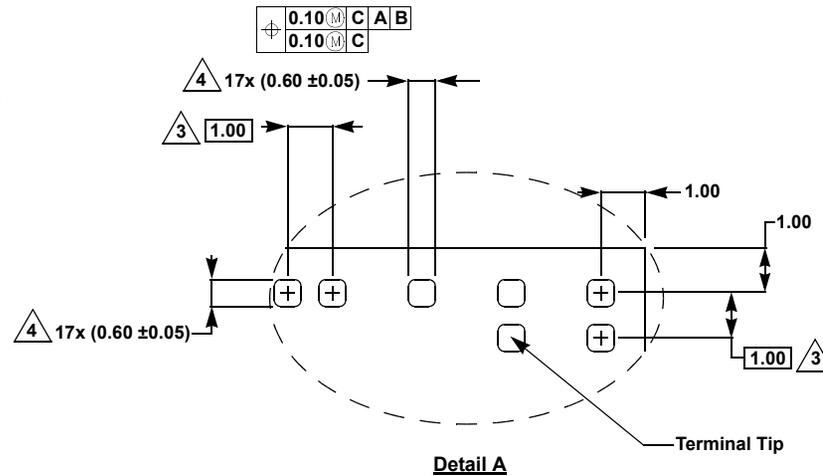
22 I/O 15mmx15mmx3.6mm Custom HDA Module

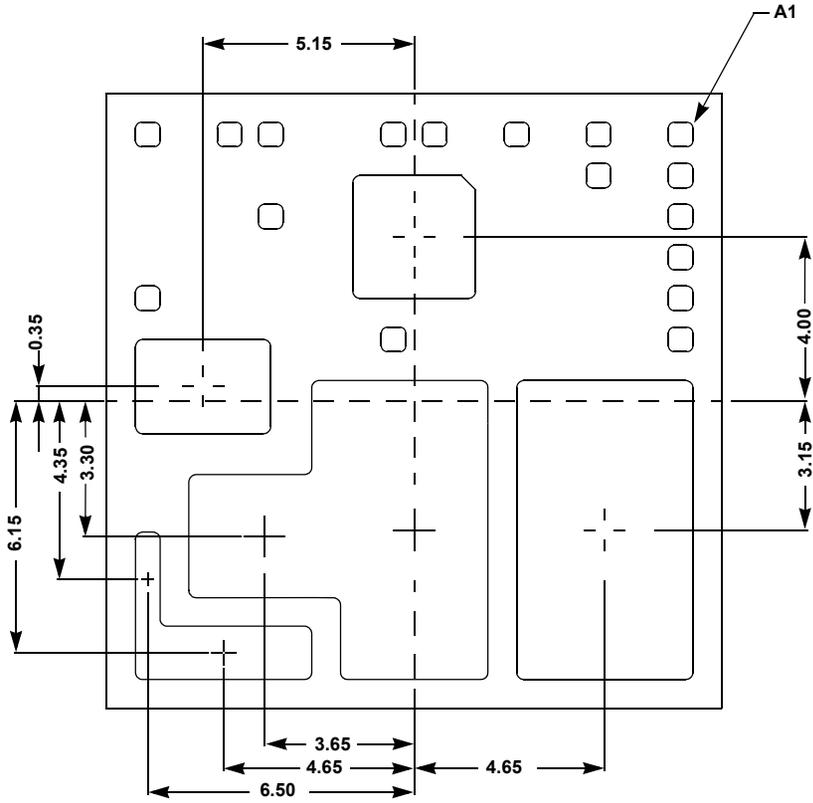
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Notes:

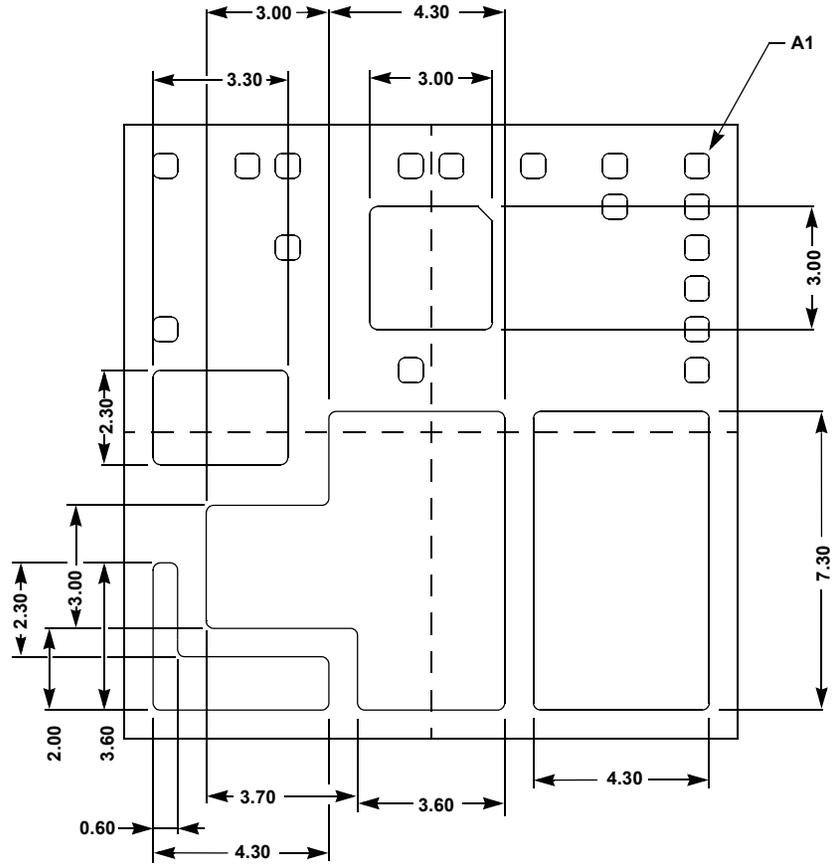
- All dimensions are in millimeters.
- All tolerances ± 0.10 mm, unless otherwise noted.
- Represents the basic land grid pitch.
- The total number of smaller I/O pads is 17. All 17 I/O's are centered in a fixed row and column matrix at 1.0mm pitch BSC.
- Dimensioning and tolerancing per ASME Y14.5M-1994.
- Tolerance for exposed DAP edge location dimension.





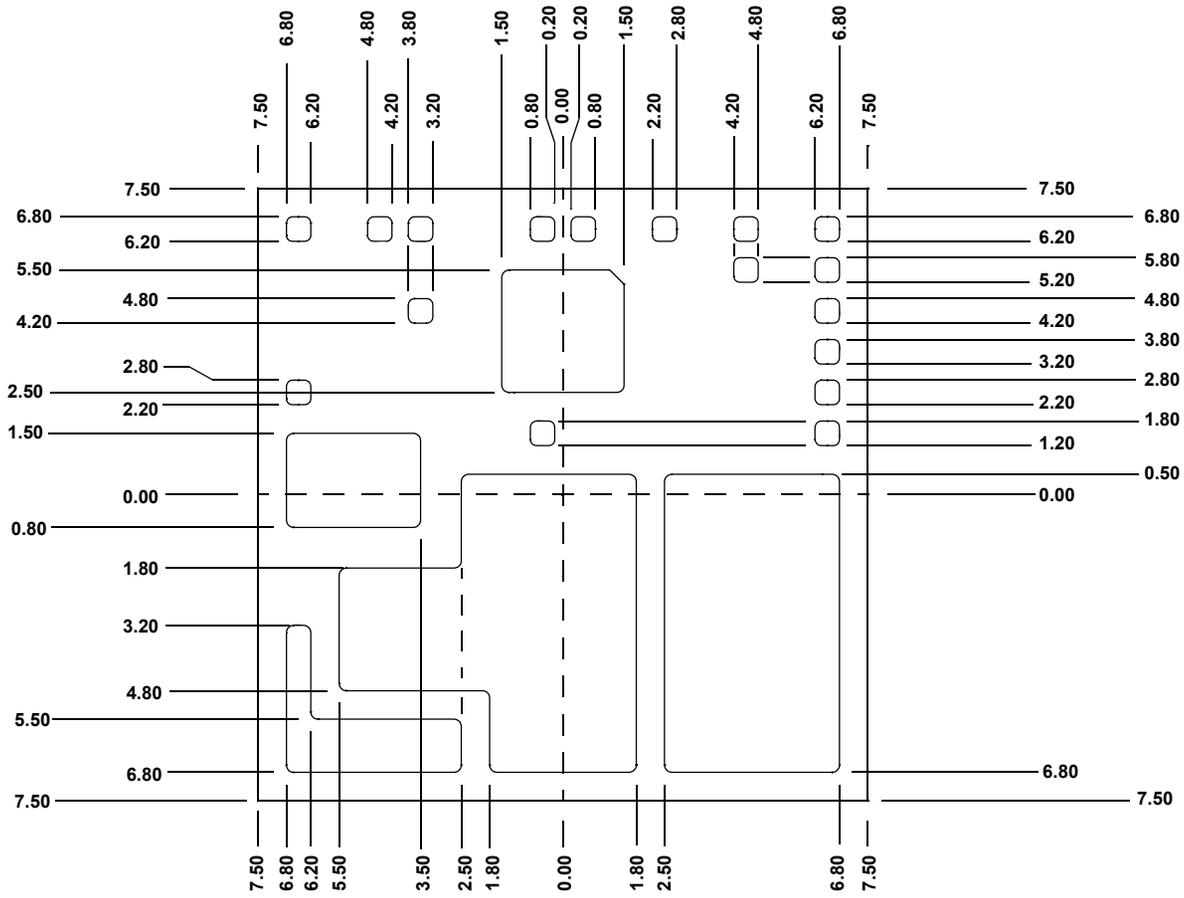
Centerline Position Details for the 5 Exposed DAPs

Bottom View

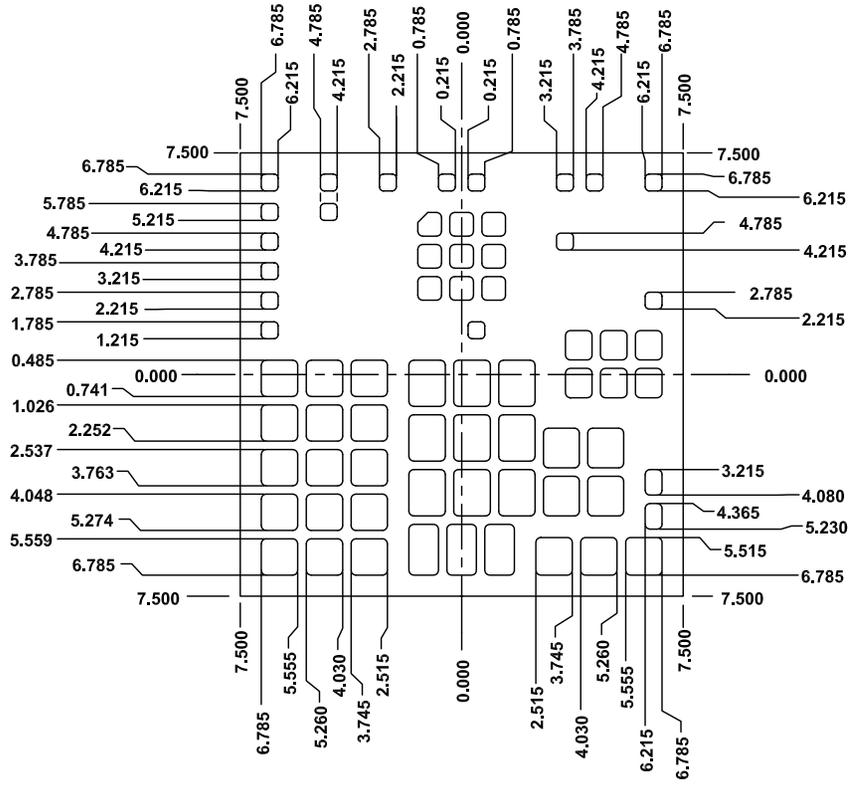


Dimensional Details for the 5 Exposed PADs

Bottom View

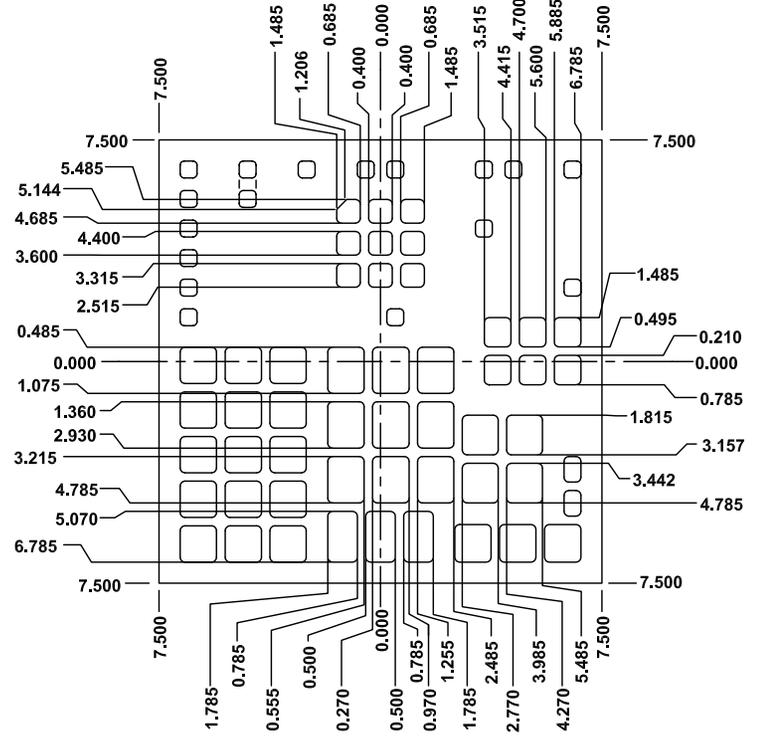


Terminal and Pad Edge Details
Bottom View



Suggested Stencil Pattern - 1

Top View



Suggested Stencil Pattern - 2

Top View

